
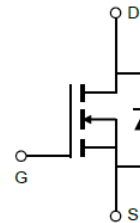




## 20V N-Channel Trench MOSFET(Preliminary)

General Description	Product Summary
<ul style="list-style-type: none"><li>Trench Power technology</li><li>Low <math>R_{DS(ON)}</math></li><li>Low Gate Charge</li><li>Optimized for fast-switching applications</li></ul> <b>Applications</b> <ul style="list-style-type: none"><li>Synchronous Rectification in DC/DC and AC/DC Converters</li><li>Isolated DC/DC Converters in Telecom and Industrial</li></ul>	$V_{DS}$ 20V $I_D$ (at $V_{GS}=10V$ ) 180A $R_{DS(ON)}$ (at $V_{GS}=10V$ ) < 2.2m $\Omega$ $R_{DS(ON)}$ (at $V_{GS}=4.5V$ ) < 2.3m $\Omega$ $R_{DS(ON)}$ (at $V_{GS}=2.5V$ ) < 3.3m $\Omega$ 100% UIS Tested 

TO-252



Part Number	Package Type	Form	Marking
TTD180N02GT	TO-252	Tape&Reel	180N02GT

### Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>B</sup>	$T_C=25^{\circ}\text{C}$	$I_D$ 46	A
	$T_C=100^{\circ}\text{C}$	46	
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	540	A
Avalanche Current <sup>A</sup>	$I_{AS}$	33	A
Single Pulse Avalanche Energy <sup>A</sup>	$L=0.3\text{mH}$ $E_{AS}$	163.4	mJ
Power Dissipation <sup>C</sup>	$T_C=25^{\circ}\text{C}$	$P_D$ 143	W
	$T_C=100^{\circ}\text{C}$	71.4	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 175	$^{\circ}\text{C}$

### Thermal Characteristics

Parameter	Symbol	Maximum	Units
Maximum Junction-to-Case	Steady-State $R_{\theta JC}$	1.05	$^{\circ}\text{C/W}$
Maximum Junction-to-Ambient	Steady-State $R_{\theta JA}$	100	

**Electrical Characteristics( $T_J = 25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions		Value			Units
				Min	Typ	Max	
STATIC PARAMETERS							
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		20			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V	T <sub>J</sub> =25°C			1	μA
			T <sub>J</sub> =100°C			25	
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V				±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA		0.5	0.7	1.2	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =30A			1.7	2.2	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =30A			1.8	2.3	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =30A			2.5	3.3	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =20A			34		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =30A, V <sub>GS</sub> =0V				1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current <sup>B</sup>					46	A
DYNAMIC PARAMETERS							
C <sub>iSS</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, f =1MHz <sub>Z</sub>			6973		pF
C <sub>oSS</sub>	Output Capacitance				1587		
C <sub>rSS</sub>	Reverse Transfer Capacitance				1316		
SWITCHING PARAMETERS							
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>GS</sub> =10V,V <sub>DS</sub> =10V, I <sub>D</sub> =50A			270		nC
Q <sub>gs</sub>	Gate Source Charge				15		
Q <sub>gd</sub>	Gate Drain Charge				50		
t <sub>D(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> =10V,V <sub>DS</sub> =10V, I <sub>D</sub> =50A, R <sub>G</sub> =3Ω			21		ns
t <sub>r</sub>	Turn-On Rise Time				28		
T <sub>D(off)</sub>	Turn-Off Delay Time				31		
t <sub>f</sub>	Turn-Off Fall Time				25		
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =50A, di/dt =100A/μs			27		ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge				24		nC

A. Single pulse width limited by maximum junction temperature.

B. The maximum current rating is package limited.

C. The power dissipation  $P_D$  is based on  $T_{J(MAX)} = 175^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

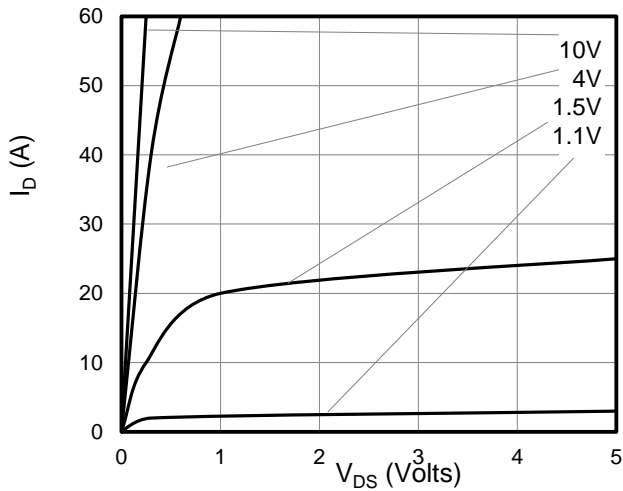


Figure 1: On-Region Characteristics

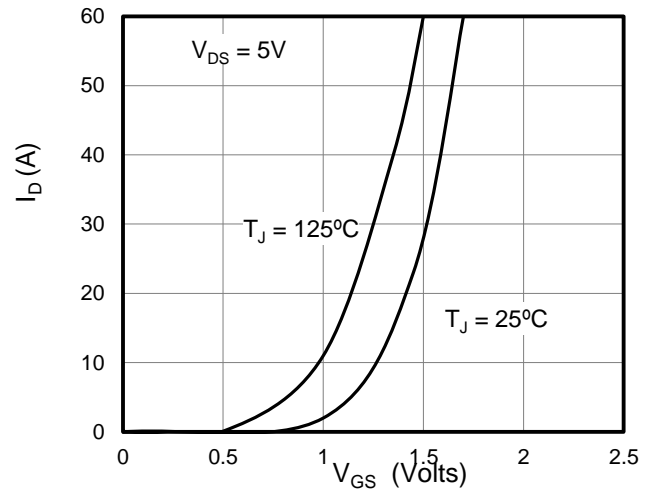


Figure 2: Transfer Characteristics

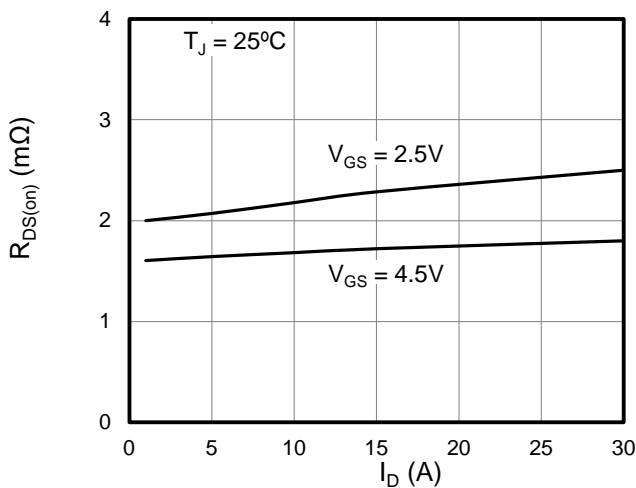


Figure 3: On-Resistance vs. Drain Current

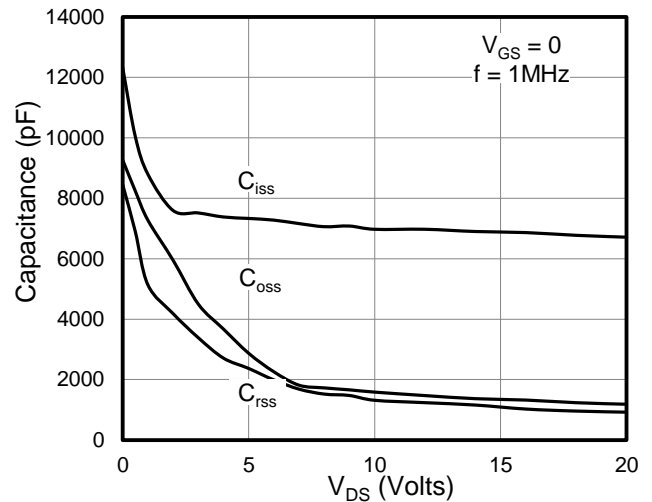


Figure 4: Capacitance Characteristics

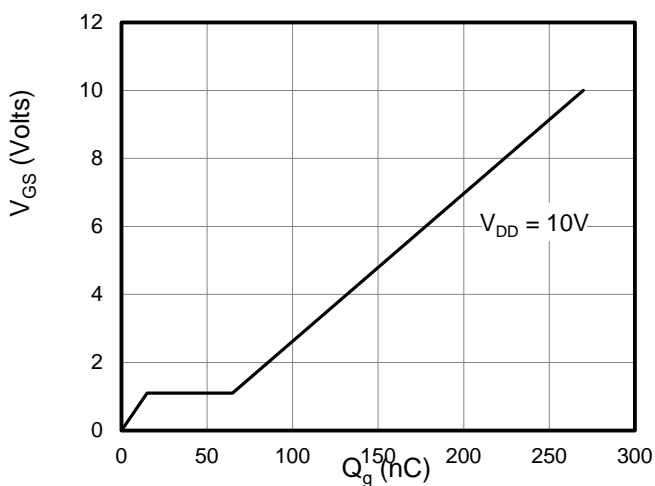


Figure 5: Gate Charge Characteristics

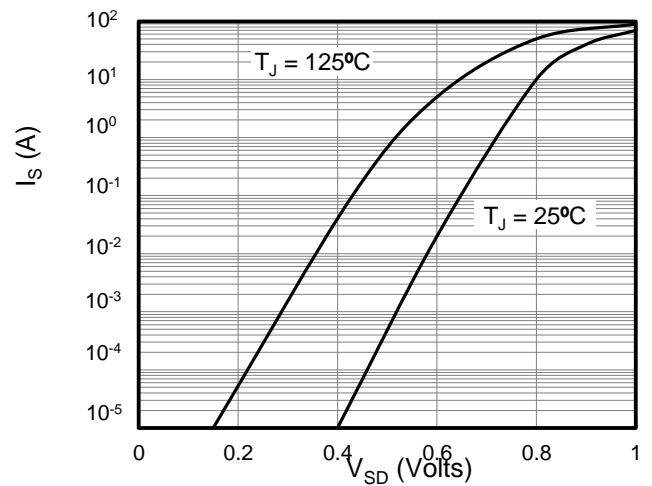


Figure 6: Body Diode Forward Voltage



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

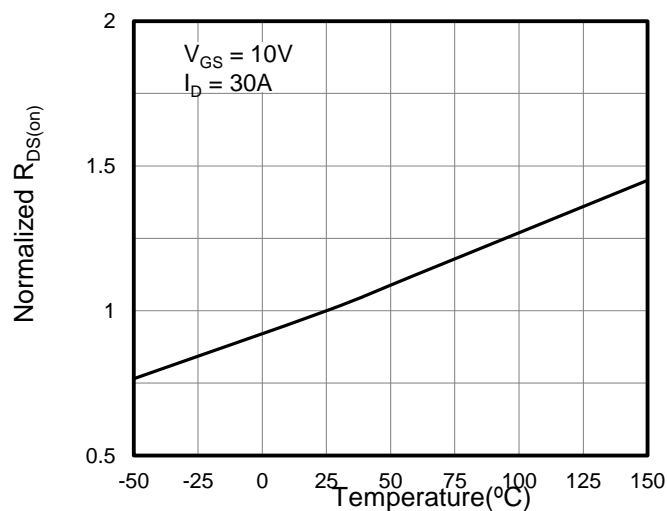


Figure 7: On-Resistance vs. Junction Temperature

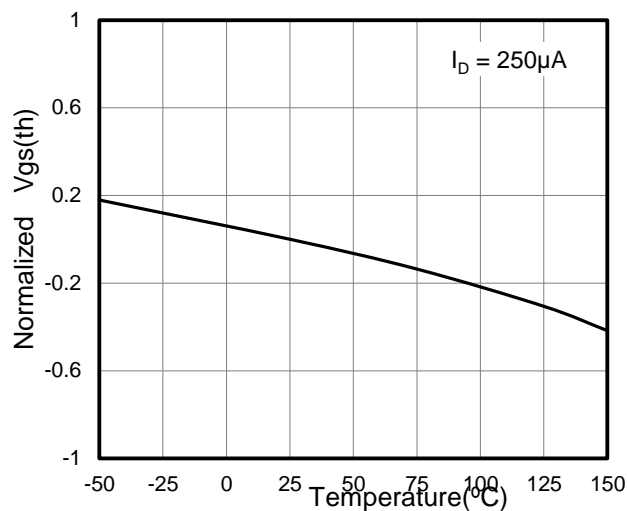
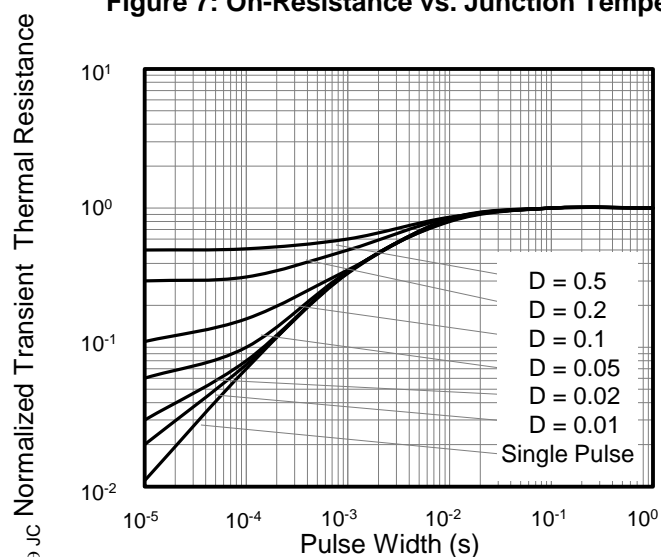
Figure 8:  $V_{GS(th)}$  vs. Junction Temperature

Figure 11: Normalized Transient Thermal Resistance

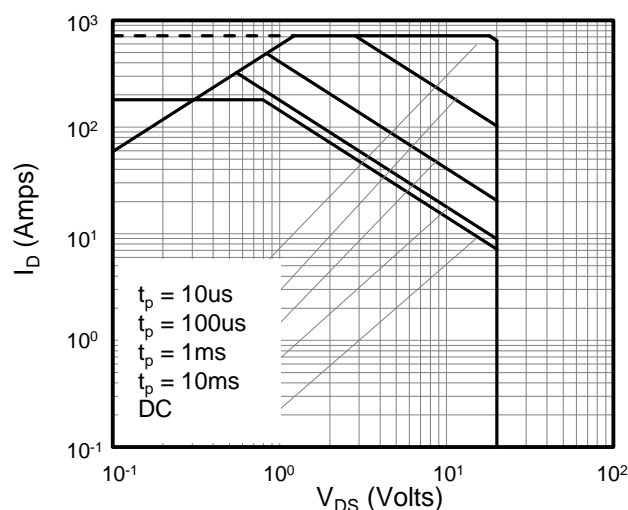


Figure 12: Safe Operating Area

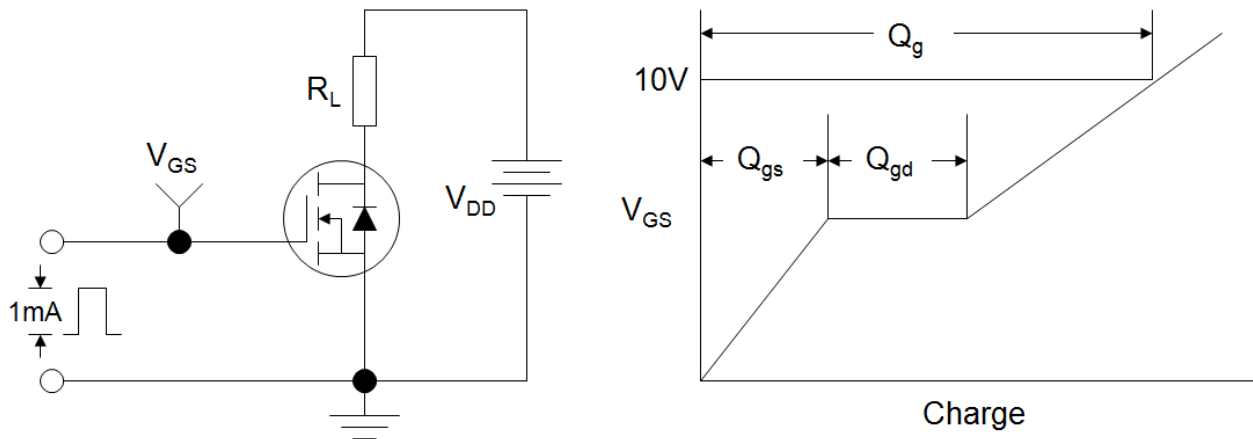


Figure A: Gate Charge Test Circuit and Waveforms

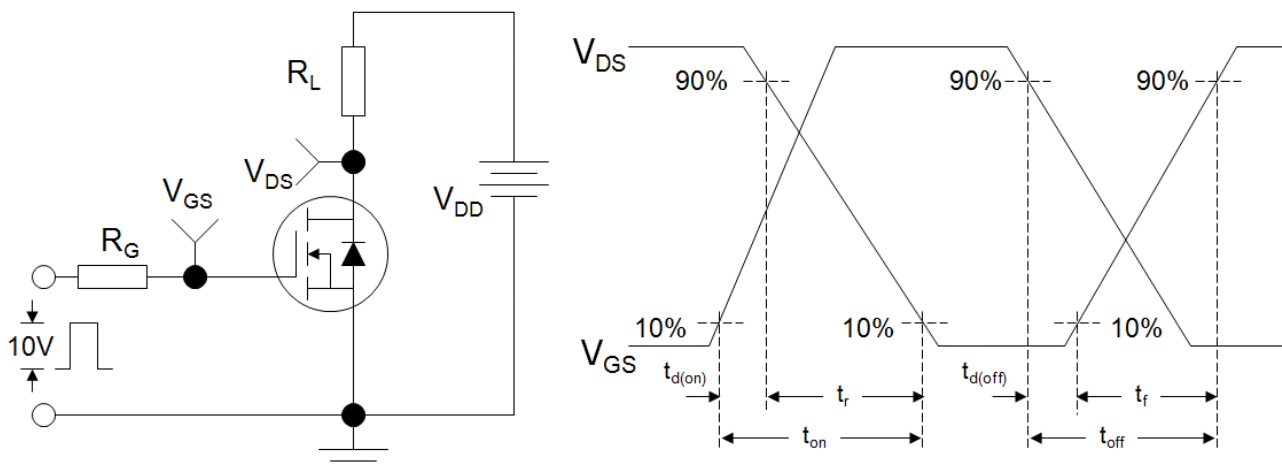


Figure B: Resistive Switching Test Circuit and Waveforms

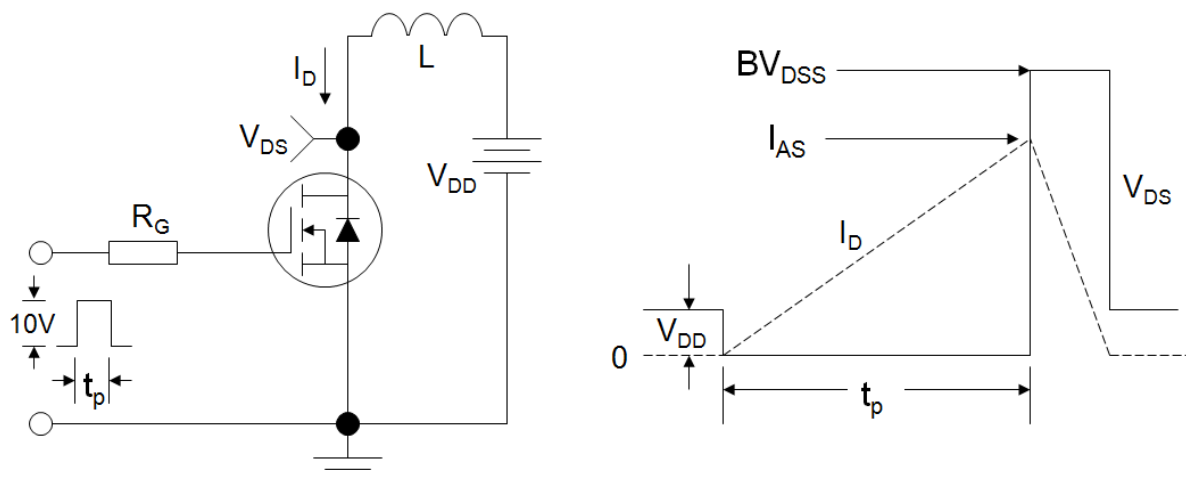
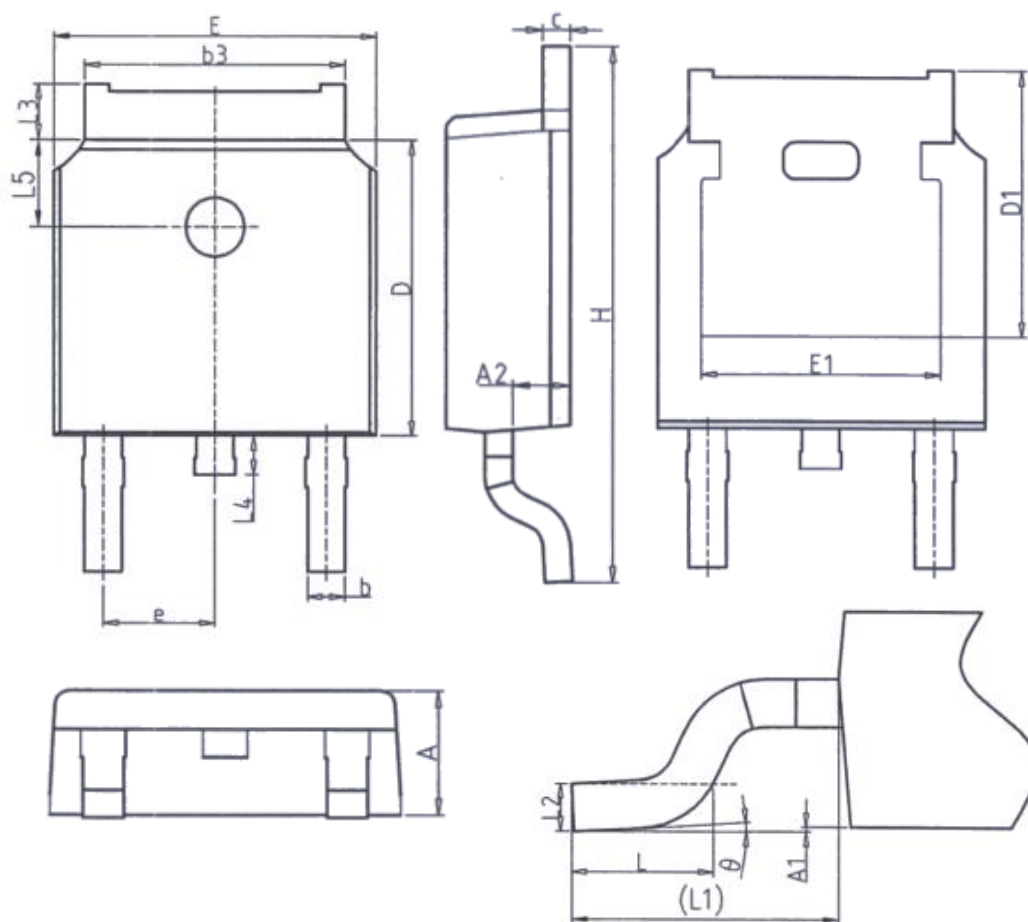


Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms



## TO-252(华天)



Unit: mm		
Symbol	Min.	Max.
A	2.20	2.40
A1	0.00	0.20
A2	0.97	1.17
b	0.68	0.90
b3	5.20	5.50
c	0.43	0.63
D	5.98	6.22
D1	5.30REF	
E	6.40	6.80
E1	4.63	-

Unit: mm		
Symbol	Min.	Max.
e	2.286BSC	
H	9.40	10.50
L	1.38	1.75
L1	2.90REF	
L2	0.51BSC	
L3	0.88	1.28
L4	-	1.00
L5	1.65	1.95
$\theta$	0°	8°



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